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(54) Title: **CHEMICALLY AMPLIFIED POSITIVE PHOTOSENSITIVE THERMOSETTING RESIN COMPOSITION METHOD OF FORMING CURED ARTICLE AND METHOD OF PRODUCING FUNCTIONAL DEVICE**

(57) Abstract: There is provided a photosensitive thermosetting resin composition used for producing a permanent film, capable of forming a resin layer which is excellent in fluidity upon heat bonding after pattern, formation and also has excellent adhesion as well as bonding properties and/or sealing properties. This composition contains a reaction product of (A) an alkali soluble resin and (C) a 10 crosslinking polyvinyl ether compound, (B) a compound generating an acid under irradiation with radiation, and (D) an epoxy resin.